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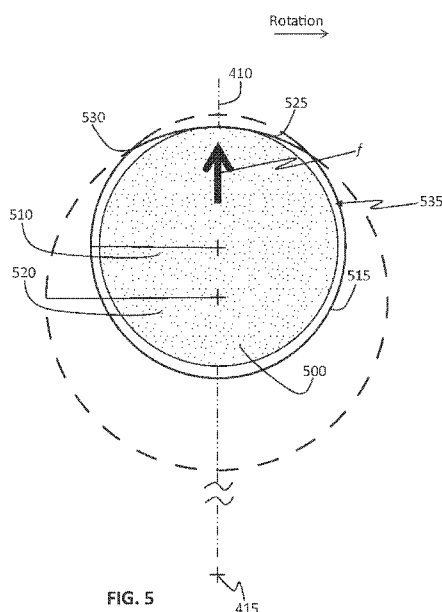
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(54) Title: WAFER CARRIER HAVING RETENTION POCKETS WITH COMPOUND RADII FOR CHEMICAL VAPOR DEPOSITION SYSTEMS



(57) Abstract: A wafer carrier for use in a chemical vapor deposition (CVD) system includes a plurality of wafer retention pockets, each having a peripheral wall surface surrounding a floor surface and defining a periphery of that wafer retention pocket. Each wafer retention pocket has a periphery with a shape defined by at least a first arc having a first radius of curvature situated around a first arc center and a second arc having a second radius of curvature situated around a second arc center. The second arc is different from the first arc, either by its radius of curvature, arc center, or both.